

Scholarship program for students attending the Contact Mechanics Symposium at the Society of Engineering Science (SES) conference, July 28 - 31, 2013

The ASME Tribology Division has initiated a new scholarship program (\$500/award) to encourage students to attend the Contact Mechanics Symposium at the SES conference at Brown University, RI, 28-31 July 2013.

Application procedure for students:

1. The student first submits her/his abstract through the conference website, to obtain a submission number. The student must be the lead author on the paper submitted to the Contact Mechanics Symposium at the SES conference to be considered for the scholarship program.
2. Then, an application package needs to be submitted containing: (1) a copy of the submitted abstract with submission number, (2) a curriculum vitae (two page max), (3) a personal statement about why the student wants to attend the Contact Mechanics Symposium at the SES conference and how it will contribute towards achieving their professional goals, and (4) a signed statement of the academic advisor stating that she/he is aware that the student is applying for this travel scholarship and the student has other sources of funding that will cover the travel expenses to the SES conference in excess of the scholarship award.

Only complete applications will be considered for award.

Review process:

A committee will review all applications based on quality and novelty of the research abstract, relevance of the research abstract to the ASME Tribology division, track-record of academic and professional success of the student (from CV), and relevance of the professional goals of the students to the ASME Tribology division.

Applications should be e-mailed by 15 May 2013 to **bart.raeymaekers@utah.edu**